

# HOT AIR LEVELING TAPE

## CM8R

CM8R is a high performance P.C. Board Tape, providing clean removal on high temperature masking applications. It is a flatback paper reinforced with polyester film, combined with an extra aggressive silicon adhesive to withstand the rigors of hot air leveling, excellent chemical and hot solder resistance, good conformability.



### Tape No: CM8R

#### Features:

Specifically designed to fully protect gold or rhodium plated P.C. Board finger contacts through flux and high heat of molten solder during solder coating and hot air leveling. For best results use with water based fluxes.

#### Technical Data:

Properties	Specification	Average Test Values
Total Thickness (mm):	0.3 ± 0.03	.031
Tensile Strength (kg / 1"):	30 min, avg	32
Elongation (%):	5 min, avg	6
Adhesion to steel (kg / 1"):	0.8 min, avg	1.3
Heat Resistance:	180° C x hr	Good
Color:	Red	
Test Method:	In accordance with <b>ASTM D-1000</b> method.	
Shelf life:	6 months when stored at 73°F and 65% relative humidity.	
Availability:	Standard 33M rolls, 3" i.d. core. Max. width 580mm	

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